# 5787082-5 ✓ ACTIVE

#### AMPLIMITE | AMPLIMITE 0.50 Series

TE Internal #: 5787082-5

PCB D-Sub Connectors, Receptacle, Cable-to-Board, 50 Position,

1.27 mm [.05 in] Centerline, 4 Row, Standard Profile, AMPLIMITE

0.50 Series

View on TE.com >



Connectors > D-Shaped Connectors > D-Sub Connectors > PCB D-Sub Connectors > D-Sub Receptacle Assembly: Right Angle, 1.27mm











Connector & Housing Type: Receptacle

Connector System: Cable-to-Board

Number of Positions: 50

Centerline (Pitch): 1.27 mm [ .05 in ]

Number of Rows: 4

All D-Sub Receptacle Assembly: Right Angle, 1.27mm (76)

#### **Features**

#### **Product Type Features**

Grounding Straps Without  Shell Type Full Metal Shell  Connector & Housing Type Receptacle  Connector System Cable-to-Board  Sealable No  Connector & Contact Terminates To Printed Circuit Board  Shielded Yes  Connector Type Connector Assembly	Grounding Indents	Without
Shell Type  Connector & Housing Type  Receptacle  Connector System  Cable-to-Board  Sealable  No  Connector & Contact Terminates To  Printed Circuit Board  Shielded  Yes	Grounded	No
Connector & Housing Type  Connector System  Cable-to-Board  Sealable  No  Connector & Contact Terminates To  Shielded  Printed Circuit Board  Yes	Grounding Straps	Without
Connector System  Cable-to-Board  No  Connector & Contact Terminates To  Printed Circuit Board  Shielded  Yes	Shell Type	Full Metal Shell
Sealable  Connector & Contact Terminates To  Printed Circuit Board  Shielded  Yes	Connector & Housing Type	Receptacle
Connector & Contact Terminates To  Printed Circuit Board  Shielded  Yes	Connector System	Cable-to-Board
Shielded Yes	Sealable	No
	Connector & Contact Terminates To	Printed Circuit Board
Connector Type Connector Assembly	Shielded	Yes
	Connector Type	Connector Assembly
Product Type Connector	Product Type	Connector

Number of Positions	50	



Bracket Material Zinc Shell Plating Finish Bright  Bracket Plating Material Nickel over Copper Post Plating Material Tin over Nickel Connector Profile Standard Shell Plating Material Nickel over Copper Shell Material Nickel over Copper Shell Material Carbon Steel Contact Features  Contact Mating Area Plating Material Gold, Gold Flash over Palladium Nickel Contact Underplating Material Nickel, Palladium Nickel PCB Contact Termination Area Plating Material Tin  Contact Base Material Phosphor Bronze  Contact Current Rating (Max) 1A 30 µin  Termination Features  Grounding Clips Without  Termination Method to Printed Circuit Board Through Hole - Solder Termination Post Length 2-54 mm[1 in]		
Bracket Material 7inc Shell Plating Finish 8inght Bracket Plating Material Nickel over Copper Post Plating Material 7in over Nickel Connector Profile Stendard Shell Plating Material Nickel over Copper Shell Material Nickel over Copper Shell Material Nickel over Copper Shell Material Contact Features  Contact Mating Area Plating Material Gold, Gold Flash over Palladium Nickel Contact Underplating Material Nickel, Palladium Nickel PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze  Contact Current Rating (Max) 1A 30 µin  Fermination Features  Grounding Clips Without Termination Post Length 254 mm(1 in)  Mechanical Attachment  Mechanical Attachment  Mechanical Attachment  Mechanical Retention Type Boardlock Mating Retention Type Boardlock Plating Material Tin over Nickel Board Mount In over Nickel Boardlock Plating Material Ninger Allong Boardlock Material Tin over Nickel Boardlock Material Without  Without	Number of Rows	4
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Bracket Plating Material Post Plating Material Tin over Nickel Connector Profile Shell Plating Material Nickel over Copper Shell Plating Material Nickel over Copper Shell Material Contact Features Contact Mating Area Plating Material Contact Underplating Material Contact Underplating Material Contact Underplating Material PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze Contact Current Rating (Max) Termination Features  Grounding Clips Without Termination Post Length Vechanical Attachment PCB Mount Alignment PCB Mount Retention With Mating Retention Type Boardlock Plating Material Nickel, Palladium Nickel Tin Tin Termination Features  Without Termination Features  Grounding Clips Without Termination Post Length Vechanical Attachment PCB Mount Retention With PCB Mount Retention Type Boardlock Mating Retention Type Boardlock Plating Material Tin over Nickel Boardlock Plating Material Tin over Nickel Boardlock Plating Material Tin over Nickel Boardlock Material Mating Alignment Without Without Without Mating Alignment Without Without Without Mating Alignment Without Without Without Without Without Mating Alignment Without Withou	Bracket Material	Zinc
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Shell Plating Material Carbon Steel  Contact Features  Contact Mating Area Plating Material Gold, Gold Flash over Palladium Nickel Contact Underplating Material Nickel, Palladium Nickel Contact Description Area Plating Material Nickel, Palladium Nickel PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze Contact Current Rating (Max) 1A 30 μin  Fermination Features  Grounding Clips Without Termination Method to Printed Circuit Board Through Hole - Solder Termination Post Length Without  Mechanical Attachment  PCB Mount Alignment Without PCB Mount Retention Type Boardlock Mating Retention Type Latch Connector Mounting Type Boardlock Plating Material Boardlock Plating Material Boardlock Material Mating Alignment Without Mating Alignment Tin over Nickel Boardlock Material Mating Alignment Without	Post Plating Material	Tin over Nickel
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Contact Features  Contact Mating Area Plating Material Gold, Gold Flash over Palladium Nickel Contact Underplating Material Nickel, Palladium Nickel PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze Contact Current Rating (Max) 1 A 30 µin  Termination Features  Grounding Clips Without Termination Method to Printed Circuit Board Through Hole - Solder Termination Post Length 2.54 mm .1 in]  Mechanical Attachment  PCB Mount Alignment Without  PCB Mount Retention Type Boardlock Mating Retention Type Board Mount Mating Retention Type Board Mount Boardlock Plating Material Tin over Nickel Boardlock Material Mating Alignment Without  Mating Alignment Copper Alloy Mating Alignment Tin over Nickel Mating Alignment Mithout  Mithout Mating Alignment Tin over Nickel Mating Alignment Mithout  Mithout Mating Alignment Mithout  Mith	Shell Plating Material	Nickel over Copper
Contact Mating Area Plating Material Gold, Gold Flash over Palladium Nickel Contact Underplating Material Nickel, Palladium Nickel PCB Contact Termination Area Plating Material Tin Contact Base Material Phosphor Bronze Contact Current Rating (Max) 1 A 30 µin  Termination Features Grounding Clips Without Termination Method to Printed Circuit Board Through Hole - Solder Termination Post Length 2.54 mm[1 in]  Wechanical Attachment PCB Mount Alignment Without PCB Mount Retention Type Board Mount Retention Type Latch Mating Retention Type Board Mount Boardlock Plating Material Tin over Nickel Boardlock Material Copper Alloy Mating Alignment Without Without Without Boardlock Material Without	Shell Material	Carbon Steel
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Contact Base Material Phosphor Bronze  Contact Current Rating (Max) 1 A 30 µin  Termination Features  Grounding Clips Without  Termination Method to Printed Circuit Board Through Hole - Solder  Termination Post Length 2.54 mm[.1 in]  Mechanical Attachment  PCB Mount Alignment Without  PCB Mount Retention With  PCB Mount Retention Type Boardlock  Mating Retention Type Latch  Connector Mounting Type Board Mount  Boardlock Plating Material Tin over Nickel  Boardlock Material Without  Mating Alignment Without	Contact Underplating Material	Nickel, Palladium Nickel
Contact Current Rating (Max)  Contact Current Rating (Max)  Termination Features  Grounding Clips  Termination Method to Printed Circuit Board  Termination Post Length  Vechanical Attachment  PCB Mount Alignment  PCB Mount Retention  PCB Mount Retention Type  Mating Retention Type  Connector Mounting Type  Boardlock Plating Material  Boardlock Material  Mating Alignment  Mithout  Copper Alloy  Mating Alignment  Mithout  Mi	PCB Contact Termination Area Plating Material	Tin
Termination Features  Grounding Clips Without Termination Method to Printed Circuit Board Termination Post Length Termination Post Length Wechanical Attachment  PCB Mount Alignment Without PCB Mount Retention PCB Mount Retention Type Boardlock Mating Retention Type Latch Connector Mounting Type Boardlock Plating Material Boardlock Material Mating Alignment Without  Copper Alloy Mating Alignment Without	Contact Base Material	Phosphor Bronze
Fermination Features  Grounding Clips Without Termination Method to Printed Circuit Board Termination Post Length  Mechanical Attachment  PCB Mount Alignment PCB Mount Retention PCB Mount Retention Type Boardlock Mating Retention Type Latch Connector Mounting Type Boardlock Plating Material Boardlock Material Mating Alignment Without  Copper Alloy Mating Alignment Without  Copper Alloy Mating Alignment Without	Contact Current Rating (Max)	1 A
Grounding Clips Termination Method to Printed Circuit Board Termination Post Length  Mechanical Attachment  PCB Mount Alignment PCB Mount Retention PCB Mount Retention PCB Mount Retention With  Mating Retention Mating Retention Type Latch Connector Mounting Type Boardlock Plating Material Boardlock Material  Mount Mating Alignment  Mithout  Without  Copper Alloy  Mating Alignment  Without		30 µin
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Termination Post Length  Wechanical Attachment  PCB Mount Alignment  PCB Mount Retention  With  PCB Mount Retention Type  Boardlock  Mating Retention Type  Latch  Connector Mounting Type  Boardlock Plating Material  Boardlock Material  Mating Alignment  Without  Without  Without  Without	Grounding Clips	Without
Mechanical Attachment  PCB Mount Alignment Without  PCB Mount Retention With  PCB Mount Retention Type Boardlock  Mating Retention With  Mating Retention Type Latch  Connector Mounting Type Board Mount  Boardlock Plating Material Tin over Nickel  Boardlock Material Copper Alloy  Mating Alignment Without	Termination Method to Printed Circuit Board	Through Hole - Solder
PCB Mount Alignment Without PCB Mount Retention With PCB Mount Retention Type Boardlock Mating Retention Muting Retention Type Latch Connector Mounting Type Board Mount Boardlock Plating Material Tin over Nickel Boardlock Material Copper Alloy Mating Alignment Without	Termination Post Length	2.54 mm[.1 in]
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PCB Mount Retention PCB Mount Retention Type Boardlock Mating Retention Mating Retention Type Latch Connector Mounting Type Boardlock Plating Material Tin over Nickel Boardlock Material Mating Alignment Without	PCB Mount Alignment	Without
Mating Retention  Mating Retention Type  Latch  Connector Mounting Type  Boardlock Plating Material  Boardlock Material  Copper Alloy  Mating Alignment  With		With
Mating Retention Type  Connector Mounting Type  Boardlock Plating Material  Boardlock Material  Copper Alloy  Mating Alignment  Latch  Latch  Latch  Copper Mount  Copper Alloy  Without	PCB Mount Retention Type	Boardlock
Connector Mounting Type  Board Mount  Tin over Nickel  Boardlock Material  Copper Alloy  Mating Alignment  Without	Mating Retention	With
Boardlock Plating Material Tin over Nickel  Boardlock Material Copper Alloy  Mating Alignment Without	Mating Retention Type	Latch
Boardlock Material Copper Alloy  Mating Alignment Without	Connector Mounting Type	Board Mount
Mating Alignment Without	Boardlock Plating Material	Tin over Nickel
	Boardlock Material	Copper Alloy
Mounting Hole Diameter 2.77 mm[.109 in]	Mating Alignment	Without
	Mounting Hole Diameter	2.77 mm[.109 in]



#### **Housing Features**

Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	Thermoplastic
Housing Color	Black

#### **Dimensions**

Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]

### **Usage Conditions**

Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]

#### Operation/Application

Circuit Application	Signal	
Chedit Application	3191141	

## **Industry Standards**

Approved Standards	LR-86179-1, UL E28476
UL Flammability Rating	UL 94V-0

#### **Packaging Features**

Packaging Method	Tube
Packaging Quantity	10

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent



chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**



























Also in the Series | AMPLIMITE 0.50 Series

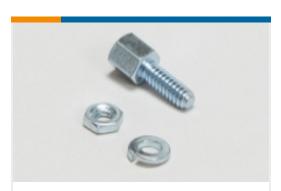








D-Sub Covers(20)



D-Sub Locking & Mounting(8)





Insertion & Extraction Tools(1)



#### **Documents**

#### **Product Drawings**

50 50SR R/A RCPT ASSY,RDSN L/F

English

#### **CAD Files**

**Customer View Model** 

ENG\_CVM\_CVM\_5787082-5\_A.2d\_dxf.zip

English

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_5787082-5\_A.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_5787082-5\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

## Datasheets & Catalog Pages

AMPLIMITE Subminiature D Connectors - .050 Series Connector

English

AMPLIMITE .050 Series D-sub Connectors QRG

English

#### **Product Specifications**

**Application Specification** 

English



Product Environmental Compliance

MD\_5787082-5\_01242017215\_dmtec

English

MD\_5787082-5\_01242017215\_dmtec

English

Agency Approvals

UL

English